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Material Content Data Sheet



Sales Product Name		TDA5235		Issued		19. July 2018		
MA#		MA001078808						
Package		PG-TSSOP-28-9		Weight*		107.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.057	3.76	3.76	37618	37618
leadframe	non noble metal	magnesium	7439-95-4	0.056	0.05		519	
	inorganic material	silicon	7440-21-3	0.243	0.22		2249	
	non noble metal	nickel	7440-02-0	1.120	1.04		10382	
	non noble metal	copper	7440-50-8	35.909	33.29	34.60	332921	346071
	noble metal	gold	7440-57-5	0.545	0.50	0.50	5049	5049
wire	noble metal	gold	7440-57-5	0.545	0.50	0.50	5049	5049
	encapsulation	organic material	carbon black	1333-86-4	0.192	0.18		1782
	plastics	epoxy resin	-	8.134	7.54		75417	
	inorganic material	silicondioxide	60676-86-0	55.724	51.68	59.40	516635	593834
leadfinish	noble metal	gold	7440-57-5	0.005	0.00		48	
	noble metal	silver	7440-22-4	0.003	0.00		26	
	noble metal	palladium	7440-05-3	0.003	0.00		30	
	non noble metal	nickel	7440-02-0	0.094	0.09	0.09	872	976
plating	noble metal	gold	7440-57-5	0.016	0.01		146	
	noble metal	silver	7440-22-4	0.009	0.01		79	
	noble metal	palladium	7440-05-3	0.010	0.01		91	
	non noble metal	nickel	7440-02-0	0.287	0.27	0.30	2663	2979
glue	plastics	epoxy resin	-	0.291	0.27		2695	
	noble metal	silver	7440-22-4	1.163	1.08	1.35	10778	13473
*deviation	< 10%			Sum in total:		100.00		1000000

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